REMARKS

In response to the Office Action date February 13, 2001, claims 15, 17, 18 22, 23, 28, 29, 33 and 34 have been amended to conform with 35 USC 112, second paragraph. Claims 26, 27, 30-32, 35 and 36 are allowed. Now new matter has been added.

Since the claims have been amended in accordance with the Examiner's suggestions, all pending claims are believed to be in condition for allowance. An indication of the same is solicited.

Attached hereto is a marked-up version of the changes made ot the specification and claims by the current amendment. The attached page is captioned "**Version with markings to show changes made**".

In the unlikely event that the transmittal letter is separated from this document and the Patent Office determines that an extension and/or other relief is required, applicant petitions for any required relief including extensions of time and authorizes the Assistant Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to **Deposit Account No. 03-1952** referencing docket no. 356972020510. However, the Assistant Commissioner is not authorized to charge the cost of the issue fee to the Deposit Account.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Claims:

15. (Amended) A method for producing a circuit component built-in module comprising the steps of:

processing a mixture comprising 70wt% to 95wt% of an inorganic filler and an uncured thermosetting resin into a first sheet having a through-hole;

filling the through-hole with a thermosetting conductive substance so as to form a second sheet having the through-hole filled with the thermosetting conductive substance;

mounting a circuit component on ~~a wiring pattern portion in~~ a first film;

positioning and superimposing the second sheet on the side of the first film where the circuit component is mounted, and superimposing a second film having a wiring pattern portion on the second sheet, thereby forming a third sheet in which the circuit component is buried; and

heating the third sheet so as to form a fourth sheet in which the thermosetting resin and the conductive substance are cured.

17. (Amended) A method for producing a circuit component built-in module comprising the steps of:

processing a mixture comprising 70wt% to 95wt% of an inorganic filler and an uncured thermosetting resin into a first sheet having a through-hole;

filling the through-hole with a thermosetting conductive substance so as to form a second sheet having the through-hole filled with the thermosetting conductive substance;

mounting a circuit component on a first film;

positioning and superimposing the second sheet on the side of the first film where the circuit component is mounted, and superimposing a second film having a wiring pattern portion on the second sheet, thereby forming a third sheet in which the circuit component is buried; and

heating the third sheet so as to form a fourth sheet in which the thermosetting resin and the conductive substance are cured ~~The method for producing a circuit component built-in module according to claim 15~~, wherein the first and second films are formed of copper foils, and the method further comprises a step of removing a portion of the copper foils ~~in a portion other than the wiring pattern portions~~ so as to form wiring patterns on which the circuit component is mounted, said step of removing the copper foils is after the step of heating the third sheet so as to form the step of forming the fourth sheet.

18. (Amended) The method for producing a circuit component built-in module according to claim 15, wherein the first and second films are formed of release films having wiring patterns formed on one principal plane thereof, and the method further comprises a step of peeling the release films from the fourth sheet, said step of peeling the release films is after the step of heating the third sheet so as to form the step of forming the fourth sheet, and the circuit component is mounted on the wiring patterns of the first film.

22. (Amended) The method for producing a circuit component built-in module according to claim 15, wherein the step of ~~forming~~ processing the mixture into the first sheet ~~further~~ comprises a step of forming the mixture into a sheet mixture and a step of heating the sheet mixture at a temperature below a cure temperature of the thermosetting resin, thereby eliminating adhesion of the sheet mixture~~, said step of heating the sheet mixture is after the step of forming the mixture into the sheet~~.

23. (Amended) The method for producing a circuit component built-in module according to claim 15, wherein the step of ~~forming~~ positioning and superimposing to form the third sheet by burying the circuit component in the second sheet is performed at a temperature below a cure temperature of the thermosetting resin.

28. (Amended) The method for producing a circuit component built-in module according to claim 26, wherein the film including the wiring pattern portion is formed of a copper foil, and the method further comprises a step of removing the copper foil in a portion other than the wiring pattern portion so as to form a wiring pattern, said step of removing the copper foil is after the step of ~~forming~~ pressing and heating to form the fifth sheet.

29. (Amended) The method for producing a circuit component built-in module according to claim 26, wherein the film including the wiring pattern portion is formed of a release film having a wiring pattern formed on one principal plane thereof, and the method further comprises a step of peeling the release film from the fifth sheet, said step of peeling the release film is after a step of ~~forming~~ pressing and heating to form the fifth sheet.

33. (Amended) The method for producing a circuit component built-in module according to claim 26, wherein the step of ~~forming~~ processing the mixture into the first sheet further comprises a step of heating the sheet mixture at a temperature below a cure temperature of the thermosetting resin, thereby eliminating adhesion of the sheet mixture, said step of heating the sheet mixture is after the step of ~~forming~~ processing the mixture into the sheet.

34. (Amended) The method for producing a circuit component built-in module according to claim 26, wherein the step of ~~forming~~ positioning and superimposing to form the third sheet by burying the circuit component in the second sheet is performed at a temperature below a cure temperature of the thermosetting resin.